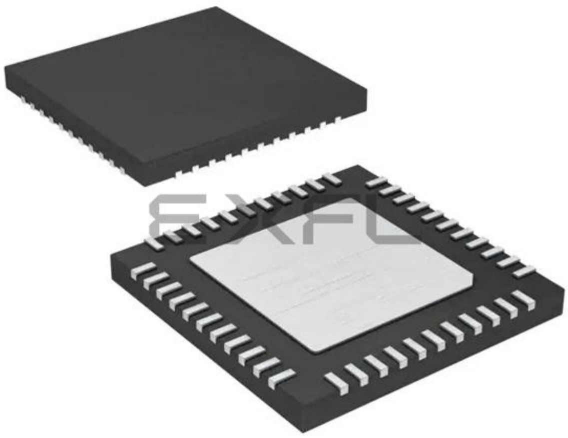

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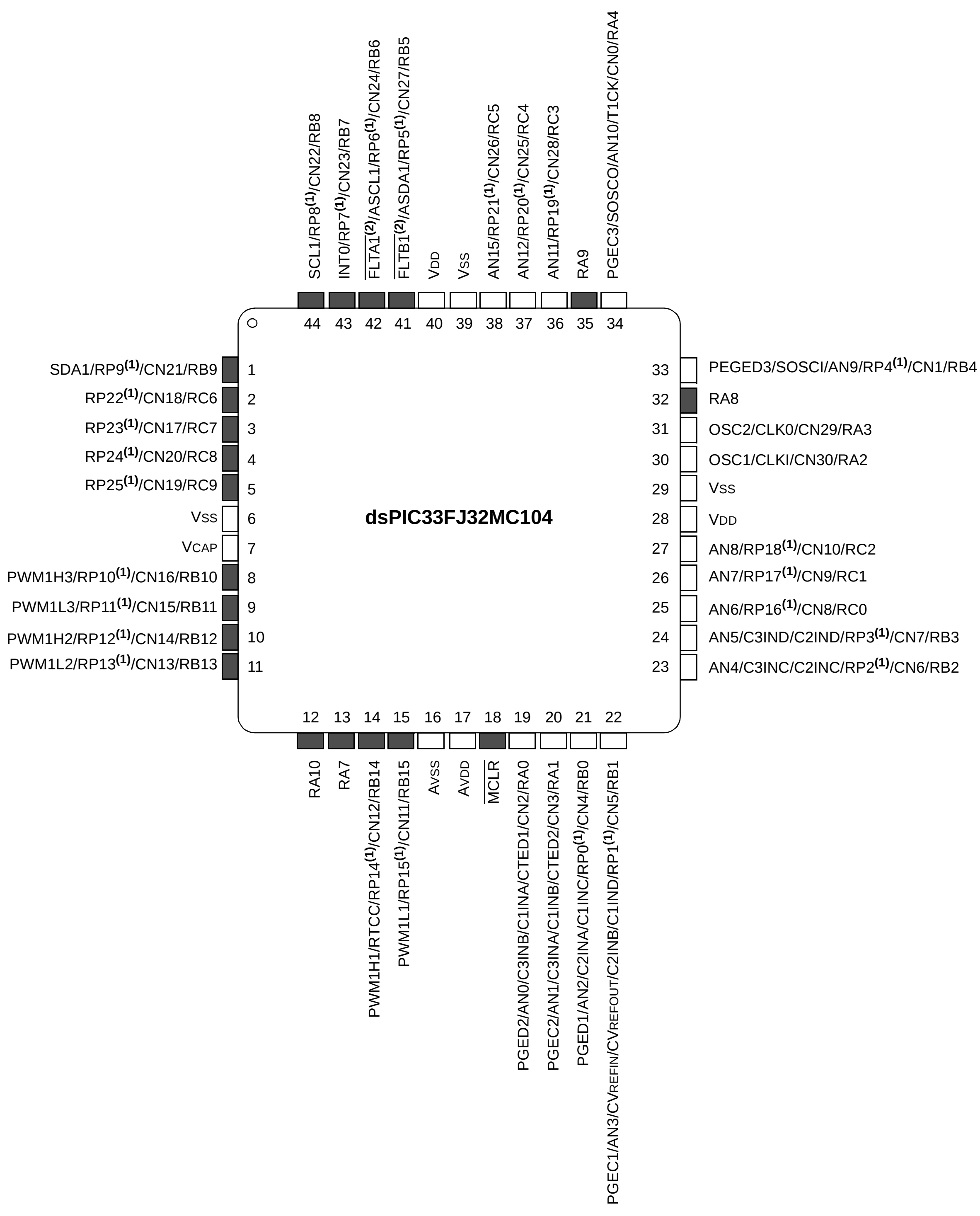
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	16 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 14x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj32gp104-e-ml

Pin Diagrams (Continued)



Note 1: The RPn pins can be used by any remappable peripheral. See Table 1 for the list of available peripherals.

2: The PWM Fault pins are enabled and asserted during any Reset event. Refer to **Section 15.2 "PWM Faults"** for more information on the PWM Faults.

REGISTER 3-1: SR: CPU STATUS REGISTER (CONTINUED)

bit 7-5	**IPL<2:0>:** CPU Interrupt Priority Level Status bits(2,3) 111 = CPU Interrupt Priority Level is 7 (15), user interrupts are disabled 110 = CPU Interrupt Priority Level is 6 (14) 101 = CPU Interrupt Priority Level is 5 (13) 100 = CPU Interrupt Priority Level is 4 (12) 011 = CPU Interrupt Priority Level is 3 (11) 010 = CPU Interrupt Priority Level is 2 (10) 001 = CPU Interrupt Priority Level is 1 (9) 000 = CPU Interrupt Priority Level is 0 (8)
bit 4	**RA:** REPEAT Loop Active bit 1 = REPEAT loop is in progress 0 = REPEAT loop is not in progress
bit 3	**N:** MCU ALU Negative bit 1 = Result was negative 0 = Result was non-negative (zero or positive)
bit 2	**OV:** MCU ALU Overflow bit This bit is used for signed arithmetic (2's complement). It indicates an overflow of a magnitude that causes the sign bit to change state. 1 = Overflow occurred for signed arithmetic (in this arithmetic operation) 0 = No overflow occurred
bit 1	**Z:** MCU ALU Zero bit 1 = An operation that affects the Z bit has set it at some time in the past 0 = The most recent operation that affects the Z bit has cleared it (i.e., a non-zero result)
bit 0	**C:** MCU ALU Carry/$\overline{\text{Borrow}}$ bit 1 = A carry-out from the Most Significant bit of the result occurred 0 = No carry-out from the Most Significant bit of the result occurred

Note 1: This bit can be read or cleared (not set).

2: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL if IPL<3> = 1. User interrupts are disabled when IPL<3> = 1.

3: The IPL<2:0> Status bits are read-only when NSTDIS = 1 (INTCON1<15>).

The `SAC` and `SAC.R` instructions store either a truncated (`SAC`), or rounded (`SAC.R`) version of the contents of the target accumulator to data memory via the X bus, subject to data saturation (see **Section 3.6.3.2 “Data Space Write Saturation”**). For the `MAC` class of instructions, the accumulator write-back operation functions in the same manner, addressing combined MCU (X and Y) data space though the X bus. For this class of instructions, the data is always subject to rounding.

3.6.3.2 Data Space Write Saturation

In addition to adder/subtracter saturation, writes to data space can also be saturated, but without affecting the contents of the source accumulator. The data space write saturation logic block accepts a 16-bit, 1.15 fractional value from the round logic block as its input, together with overflow status from the original source (accumulator) and the 16-bit round adder. These inputs are combined and used to select the appropriate 1.15 fractional value as output to write to data space memory.

If the SATDW bit in the CORCON register is set, data (after rounding or truncation) is tested for overflow and adjusted accordingly:

- For input data greater than 0x007FFF, data written to memory is forced to the maximum positive 1.15 value, 0x7FFF.
- For input data less than 0xFF8000, data written to memory is forced to the maximum negative 1.15 value, 0x8000.

The MSb of the source (bit 39) is used to determine the sign of the operand being tested.

If the SATDW bit in the CORCON register is not set, the input data is always passed through unmodified under all conditions.

3.6.4 BARREL SHIFTER

The barrel shifter can perform up to 16-bit arithmetic or logic right shifts, or up to 16-bit left shifts, in a single cycle. The source can be either of the two DSP accumulators or the X bus (to support multi-bit shifts of register or memory data).

The shifter requires a signed binary value to determine both the magnitude (number of bits) and direction of the shift operation. A positive value shifts the operand right. A negative value shifts the operand left. A value of ‘`0`’ does not modify the operand.

The barrel shifter is 40 bits wide, thereby obtaining a 40-bit result for DSP shift operations and a 16-bit result for MCU shift operations. Data from the X bus is presented to the barrel shifter between Bit Positions 16 and 31 for right shifts, and between Bit Positions 0 and 16 for left shifts.

REGISTER 9-3: PMD3: PERIPHERAL MODULE DISABLE CONTROL REGISTER 3

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	U-0
—	—	—	—	—	CMPMD	RTCCMD	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as ‘0’

bit 10 **CMPMD:** Comparator Module Disable bit
1 = Comparator module is disabled
0 = Comparator module is enabled

bit 9 **RTCCMD:** RTCC Module Disable bit
1 = RTCC module is disabled
0 = RTCC module is enabled

bit 8-0 **Unimplemented:** Read as ‘0’

REGISTER 9-4: PMD4: PERIPHERAL MODULE DISABLE CONTROL REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	U-0	U-0
—	—	—	—	—	CTMUMD	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-3 **Unimplemented:** Read as ‘0’

bit 2 **CTMUMD:** CTMU Module Disable bit
1 = CTMU module is disabled
0 = CTMU module is enabled

bit 1-0 **Unimplemented:** Read as ‘0’

NOTES:

10.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORTx, LATx and TRISx registers for data control, some port pins can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs higher than V_{DD} (e.g., 5V) on any desired 5V tolerant pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum V_{IH} specification.

See **"Pin Diagrams"** for the available pins and their functionality.

10.2 Configuring Analog Port Pins

The AD1PCFGL and TRISx registers control the operation of the Analog-to-Digital port pins. The port pins that are to function as analog inputs must have their corresponding TRISx bit set (input). If the TRISx bit is cleared (output), the digital output level (V_{OH} or V_{OL}) will be converted.

The AD1PCFGL register has a default value of 0x0000; therefore, all pins that share ANx functions are analog (not digital) by default.

When the PORTx register is read, all pins configured as analog input channels will read as cleared (a low level).

Pins configured as digital inputs will not convert an analog input. Analog levels on any pin defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

10.2.1 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically this instruction would be a NOP. A demonstration is shown in Example 10-1.

10.3 Input Change Notification (ICN)

The Input Change Notification function of the I/O ports allows the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices to generate interrupt requests to the processor in response to a Change-of-State (COS) on selected input pins. This feature can detect input Change-of-States, even in Sleep mode, when the clocks are disabled. Depending on the device pin count, up to 21 external signals (CNx pin) can be selected (enabled) for generating an interrupt request on a Change-of-State.

Four control registers are associated with the CN module. The CNEN1 and CNEN2 registers contain the interrupt enable control bits for each of the CN input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

Each CN pin also has a weak pull-up connected to it. The pull-ups act as a current source connected to the pin and eliminate the need for external resistors when push button or keypad devices are connected. The pull-ups are enabled separately using the CNPU1 and CNPU2 registers, which contain the control bits for each of the CN pins. Setting any of the control bits enables the weak pull-ups for the corresponding pins.

Note:	Pull-ups on Input Change Notification pins should always be disabled when the port pin is configured as a digital output.

EXAMPLE 10-1: PORT WRITE/READ EXAMPLE

```
MOV   0xFF00, W0         ; Configure PORTB<15:8> as inputs
MOV   W0, TRISBB         ; and PORTB<7:0> as outputs
NOP                      ; Delay 1 cycle
btss  PORTB, #13         ; Next Instruction
```

REGISTER 10-5: RPINR7: PERIPHERAL PIN SELECT INPUT REGISTER 7

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	IC2R4	IC2R3	IC2R2	IC2R1	IC2R0
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	IC1R4	IC1R3	IC1R2	IC1R1	IC1R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12-8 **IC2R<4:0>:** Assign Input Capture 2 (IC2) to the Corresponding RPn Pin bits
11111 = Input tied to Vss
11110 = Reserved
.
.
.
11010 = Reserved
11001 = Input tied to RP25
.
.
.
00001 = Input tied to RP1
00000 = Input tied to RP0

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4-0 **IC1R<4:0>:** Assign Input Capture 1 (IC1) to the Corresponding RPn Pin bits
11111 = Input tied to Vss
11110 = Reserved
.
.
.
11010 = Reserved
11001 = Input tied to RP25
.
.
.
00001 = Input tied to RP1
00000 = Input tied to RP0

14.1 Output Compare Modes

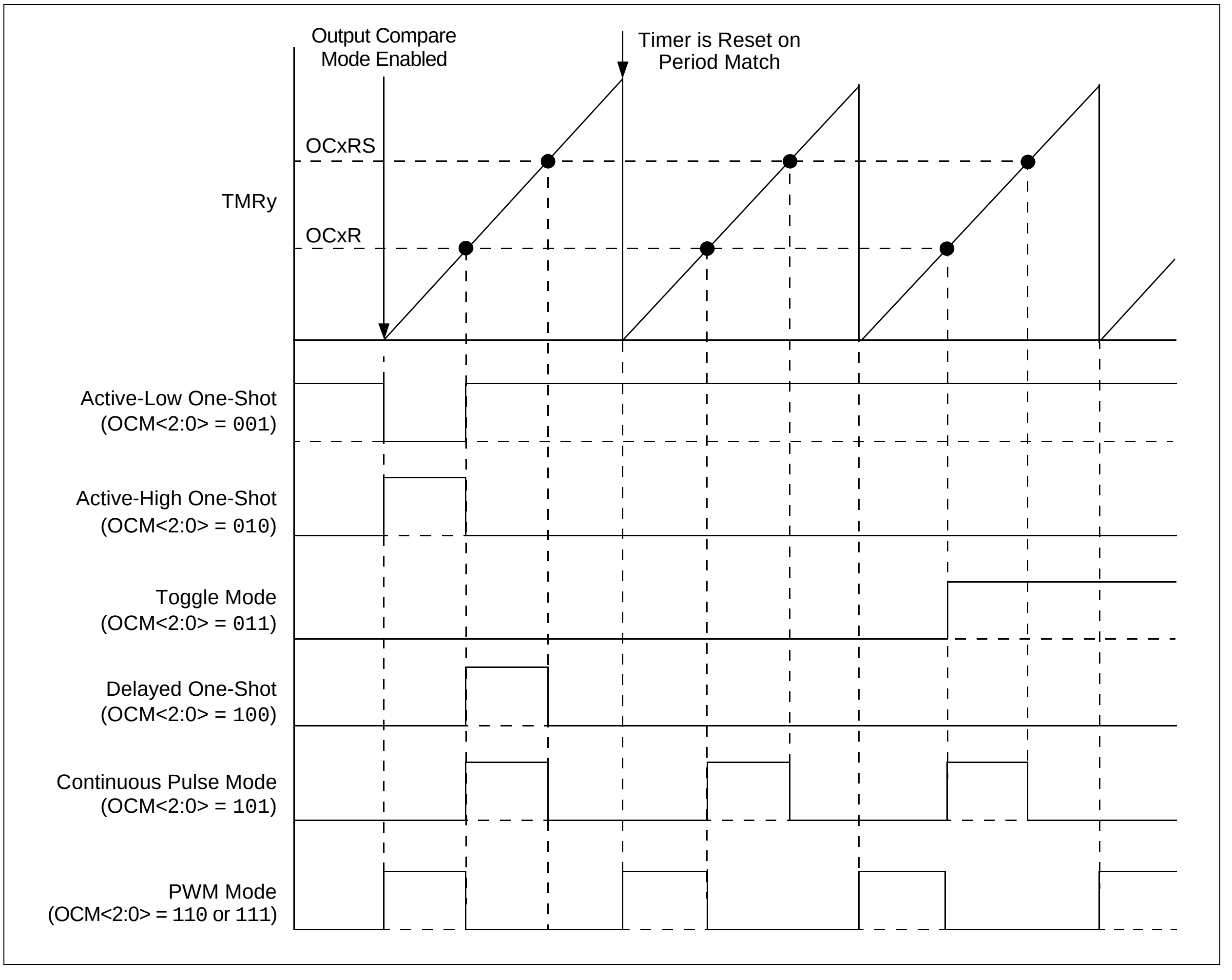
Configure the Output Compare modes by setting the appropriate Output Compare Mode bits (OCM<2:0>) in the Output Compare x Control (OCxCON<2:0>) register. Table 14-1 lists the different bit settings for the Output Compare modes. Figure 14-2 illustrates the output compare operation for various modes. The user application must disable the associated timer when writing to the Output Compare Control registers to avoid malfunctions.

> **Note:** See **"Output Compare"** in the *"dsPIC33/PIC24 Family Reference Manual"* (DS70209) for OCxR and OCxRS register restrictions.

TABLE 14-1: OUTPUT COMPARE x MODES

OCM<2:0>	Mode	OCx Pin Initial State	OCx Interrupt Generation
000	Module Disabled	Controlled by GPIO register	—
001	Active-Low One-Shot	0	OCx Rising Edge
010	Active-High One-Shot	1	OCx Falling Edge
011	Toggle	Current output is maintained	OCx Rising and Falling Edge
100	Delayed One-Shot	0	OCx Falling Edge
101	Continuous Pulse	0	OCx Falling Edge
110	PWM without Fault Protection	0, if OCxR is zero 1, if OCxR is non-zero	No Interrupt
111	PWM with Fault Protection	0, if OCxR is zero 1, if OCxR is non-zero	OCFA Falling Edge for OC1 to OC4

FIGURE 14-2: OUTPUT COMPARE x OPERATION



14.2 Output Compare Control Register

REGISTER 14-1: OCxCON: OUTPUT COMPARE x CONTROL REGISTER

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	OCSIDL	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R-0, HC	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	OCFLT	OCTSEL	OCM2	OCM1	OCM0
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13 **OCSIDL:** Output Compare x Stop in Idle Mode Control bit
1 = Output Compare x will halt in CPU Idle mode
0 = Output Compare x will continue to operate in CPU Idle mode

bit 12-5 **Unimplemented:** Read as ‘0’

bit 4 **OCFLT:** PWM Fault Condition Status bit
1 = PWM Fault condition has occurred (cleared in hardware only)
0 = No PWM Fault condition has occurred
(This bit is only used when OCM<2:0> = 111.)

bit 3 **OCTSEL:** Output Compare x Timer Selection bit
1 = Timer3 is the clock source for Output Compare x
0 = Timer2 is the clock source for Output Compare x

bit 2-0 **OCM<2:0>:** Output Compare x Mode Select bits
111 = PWM mode on OCx, Fault pin is enabled
110 = PWM mode on OCx, Fault pin is disabled
101 = Initializes OCx pin low, generates continuous output pulses on OCx pin
100 = Initializes OCx pin low, generates single output pulse on OCx pin
011 = Compare event toggles OCx pin
010 = Initializes OCx pin high, compare event forces OCx pin low
001 = Initializes OCx pin low, compare event forces OCx pin high
000 = Output Compare x channel is disabled

18.1 UART Helpful Tips

1. In multi-node, direct connect UART networks, UART receive inputs react to the complementary logic level defined by the URXINV bit (UxMODE<4>), which defines the Idle state, the default of which is logic high (i.e., URXINV = 0). Because remote devices do not initialize at the same time, it is likely that one of the devices, because the RX line is floating, will trigger a Start bit detection and will cause the first byte received after the device has been initialized to be invalid. To avoid this situation, the user should use a pull-up or pull-down resistor on the RX pin depending on the value of the URXINV bit.
   a) If URXINV = 0, use a pull-up resistor on the RX pin.
   b) If URXINV = 1, use a pull-down resistor on the RX pin.
2. The first character received on a wake-up from Sleep mode caused by activity on the UxRX pin of the UART module will be invalid. In Sleep mode, peripheral clocks are disabled. By the time the oscillator system has restarted and stabilized from Sleep mode, the baud rate bit sampling clock, relative to the incoming UxRX bit timing, is no longer synchronized, resulting in the first character being invalid; this is to be expected.

18.2 UART Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en554109

18.2.1 KEY RESOURCES

- **"UART"** (DS70188) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related *"dsPIC33/PIC24 Family Reference Manual"* sections
- Development Tools

21.1 RTCC Module Registers

The RTCC module registers are organized into three categories:

- RTCC Control Registers
- RTCC Value Registers
- Alarm Value Registers

21.1.1 REGISTER MAPPING

To limit the register interface, the RTCC Timer and Alarm Time registers are accessed through corresponding register pointers. The RTCC Value register window (RTCVALH and RTCVALL) uses the RTCPTR bits (RCFGCAL<9:8>) to select the desired Timer register pair (see Table 21-1).

By writing the RTCVALH byte, the RTCC Pointer value (RTCPTR<1:0> bits) decrements by one until it reaches '00'. Once it reaches '00', the MINUTES and SECONDS value will be accessible through RTCVALH and RTCVALL until the pointer value is manually changed.

TABLE 21-1: RTCVAL REGISTER MAPPING

RTCPTR <1:0>	RTCC Value Register Window	
	RTCVAL<15:8>	RTCVAL<7:0>
00	MINUTES	SECONDS
01	WEEKDAY	HOURS
10	MONTH	DAY
11	—	YEAR

The Alarm Value register window (ALRMVALH and ALRMVALL) uses the ALRMPTR bits (ALCFGRPT<9:8>) to select the desired Alarm register pair (see Table 21-2).

By writing the ALRMVALH byte, the Alarm Pointer value (ALRMPTR<1:0> bits) decrements by one until it reaches '00'. Once it reaches '00', the ALRMMIN and ALRMSEC value will be accessible through ALRMVALH and ALRMVALL until the pointer value is manually changed.

TABLE 21-2: ALRMVAL REGISTER MAPPING

ALRMPTR <1:0>	Alarm Value Register Window	
	ALRMVAL<15:8>	ALRMVAL<7:0>
00	ALRMMIN	ALRMSEC
01	ALRMWD	ALRMHR
10	ALRMMNTH	ALRMDAY
11	—	—

Considering that the 16-bit core does not distinguish between 8-bit and 16-bit read operations, the user must be aware that when reading either the ALRMVALH or ALRMVALL, bytes will decrement the ALRMPTR<1:0> value. The same applies to the RTCVALH or RTCVALL bytes with the RTCPTR<1:0> being decremented.

> **Note:** This only applies to read operations and not write operations.

21.1.2 WRITE LOCK

In order to perform a write to any of the RTCC Timer registers, the RTCWREN bit (RCFGCAL<13>) must be set (refer to Example 21-1).

> **Note:** To avoid accidental writes to the timer, it is recommended that the RTCWREN bit (RCFGCAL<13>) is kept clear at any other time. For the RTCWREN bit to be set, there is only 1 instruction cycle time window allowed between the 55h/AA sequence and the setting of RTCWREN; therefore, it is recommended that code follow the procedure in Example 21-1.

EXAMPLE 21-1: SETTING THE RTCWREN BIT

```
    MOV     #NVMKEY, W1       ;move the address of NVMKEY into W1
    MOV     #0x55, W2
    MOV     #0xAA, W3
    MOV     W2, [W1]          ;start 55/AA sequence
    MOV     W3, [W1]
    BSET    RCFGCAL, #13      ;set the RTCWREN bit
```

REGISTER 21-4: RTCVAL (WHEN RTCPTR<1:0> = 11): RTCC YEAR VALUE REGISTER[1]

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
YRTEN3	YRTEN2	YRTEN1	YRTEN0	YRONE3	YRONE2	YRONE1	YRONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7-4 **YRTEN<3:0>:** Binary Coded Decimal Value of Year's Tens Digit bits
Contains a value from 0 to 9.

bit 3-0 **YRONE<3:0>:** Binary Coded Decimal Value of Year's Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = 1.

REGISTER 21-5: RTCVAL (WHEN RTCPTR<1:0> = 10): RTCC MONTH AND DAY VALUE REGISTER[1]

U-0	U-0	U-0	R-x	R-x	R-x	R-x	R-x
—	—	—	MTHTEN0	MTHONE3	MTHONE2	MTHONE1	MTHONE0
bit 15							bit 8

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	DAYTEN1	DAYTEN0	DAYONE3	DAYONE2	DAYONE1	DAYONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12 **MTHTEN0:** Binary Coded Decimal Value of Month's Tens Digit bit
Contains a value of 0 or 1.

bit 11-8 **MTHONE<3:0>:** Binary Coded Decimal Value of Month's Ones Digit bits
Contains a value from 0 to 9.

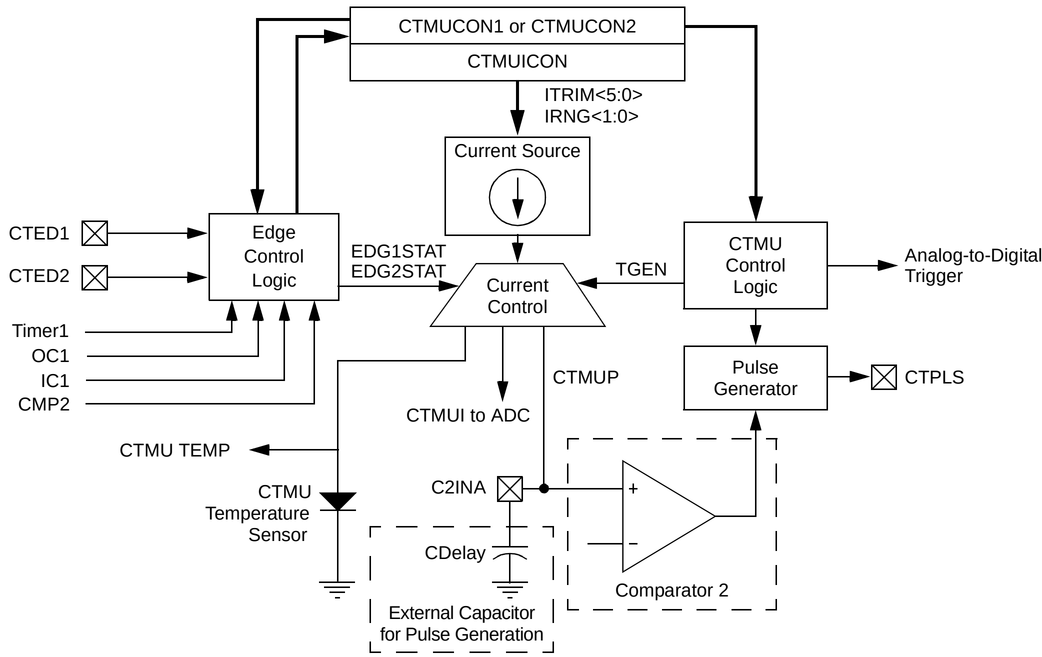
bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **DAYTEN<1:0>:** Binary Coded Decimal Value of Day's Tens Digit bits
Contains a value from 0 to 3.

bit 3-0 **DAYONE<3:0>:** Binary Coded Decimal Value of Day's Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = 1.

FIGURE 22-1: CTMU BLOCK DIAGRAM



Current Control Selection	TGEN	EDG1STAT, EDG2STAT
CTMU TEMP	0	EDG1STAT = EDG2STAT
CTMUI	0	EDG1STAT ≠ EDG2STAT
CTMUP	1	EDG1STAT ≠ EDG2STAT
No Connect	1	EDG1STAT = EDG2STAT

TABLE 24-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
66	RRNC	RRNC f	f = Rotate Right (No Carry) f	1	1	N,Z
		RRNC f,WREG	WREG = Rotate Right (No Carry) f	1	1	N,Z
		RRNC Ws,Wd	Wd = Rotate Right (No Carry) Ws	1	1	N,Z
67	SAC	SAC Acc,#Slit4,Wdo	Store Accumulator	1	1	None
		SAC.R Acc,#Slit4,Wdo	Store Rounded Accumulator	1	1	None
68	SE	SE Ws,Wnd	Wnd = sign-extended Ws	1	1	C,N,Z
69	SETM	SETM f	f = 0xFFFF	1	1	None
		SETM WREG	WREG = 0xFFFF	1	1	None
		SETM Ws	Ws = 0xFFFF	1	1	None
70	SFTAC	SFTAC Acc,Wn	Arithmetic Shift Accumulator by (Wn)	1	1	OA,OB,OAB, SA,SB,SAB
		SFTAC Acc,#Slit6	Arithmetic Shift Accumulator by Slit6	1	1	OA,OB,OAB, SA,SB,SAB
71	SL	SL f	f = Left Shift f	1	1	C,N,OV,Z
		SL f,WREG	WREG = Left Shift f	1	1	C,N,OV,Z
		SL Ws,Wd	Wd = Left Shift Ws	1	1	C,N,OV,Z
		SL Wb,Wns,Wnd	Wnd = Left Shift Wb by Wns	1	1	N,Z
		SL Wb,#lit5,Wnd	Wnd = Left Shift Wb by lit5	1	1	N,Z
72	SUB	SUB Acc	Subtract Accumulators	1	1	OA,OB,OAB, SA,SB,SAB
		SUB f	f = f – WREG	1	1	C,DC,N,OV,Z
		SUB f,WREG	WREG = f – WREG	1	1	C,DC,N,OV,Z
		SUB #lit10,Wn	Wn = Wn – lit10	1	1	C,DC,N,OV,Z
		SUB Wb,Ws,Wd	Wd = Wb – Ws	1	1	C,DC,N,OV,Z
		SUB Wb,#lit5,Wd	Wd = Wb – lit5	1	1	C,DC,N,OV,Z
73	SUBB	SUBB f	f = f – WREG – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB f,WREG	WREG = f – WREG – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB #lit10,Wn	Wn = Wn – lit10 – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB Wb,Ws,Wd	Wd = Wb – Ws – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB Wb,#lit5,Wd	Wd = Wb – lit5 – ($\overline{C}$)	1	1	C,DC,N,OV,Z
74	SUBR	SUBR f	f = WREG – f	1	1	C,DC,N,OV,Z
		SUBR f,WREG	WREG = WREG – f	1	1	C,DC,N,OV,Z
		SUBR Wb,Ws,Wd	Wd = Ws – Wb	1	1	C,DC,N,OV,Z
		SUBR Wb,#lit5,Wd	Wd = lit5 – Wb	1	1	C,DC,N,OV,Z
75	SUBBR	SUBBR f	f = WREG – f – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBBR f,WREG	WREG = WREG – f – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBBR Wb,Ws,Wd	Wd = Ws – Wb – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBBR Wb,#lit5,Wd	Wd = lit5 – Wb – ($\overline{C}$)	1	1	C,DC,N,OV,Z
76	SWAP	SWAP.b Wn	Wn = nibble swap Wn	1	1	None
		SWAP Wn	Wn = byte swap Wn	1	1	None
77	TBLRDH	TBLRDH Ws,Wd	Read Prog<23:16> to Wd<7:0>	1	2	None
78	TBLRDL	TBLRDL Ws,Wd	Read Prog<15:0> to Wd	1	2	None
79	TBLWTH	TBLWTH Ws,Wd	Write Ws<7:0> to Prog<23:16>	1	2	None
80	TBLWTL	TBLWTL Ws,Wd	Write Ws to Prog<15:0>	1	2	None
81	ULNK	ULNK	Unlink Frame Pointer	1	1	None
82	XOR	XOR f	f = f .XOR. WREG	1	1	N,Z
		XOR f,WREG	WREG = f .XOR. WREG	1	1	N,Z
		XOR #lit10,Wn	Wd = lit10 .XOR. Wd	1	1	N,Z
		XOR Wb,Ws,Wd	Wd = Wb .XOR. Ws	1	1	N,Z
		XOR Wb,#lit5,Wd	Wd = Wb .XOR. lit5	1	1	N,Z
83	ZE	ZE Ws,Wnd	Wnd = Zero-extend Ws	1	1	C,Z,N

TABLE 26-6: DC CHARACTERISTICS: OPERATING CURRENT (IDD) (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typical(1)**	**Max**	**Units**	**Conditions**		
Operating Current (IDD)(2) – dsPIC33FJ32(GP/MC)10X Devices						
DC20d	1	2	mA	-40°C	3.3V	LPRC (32.768 kHz)(3)
DC20a	1	2	mA	+25°C		
DC20b	1.1	2	mA	+85°C		
DC20c	1.3	2	mA	+125°C		
DC21d	1.7	3	mA	-40°C	3.3V	1 MIPS(3)
DC21a	2.3	3	mA	+25°C		
DC21b	2.3	3	mA	+85°C		
DC21c	2.4	3	mA	+125°C		
DC22d	7	8.5	mA	-40°C	3.3V	4 MIPS(3)
DC22a	7	8.5	mA	+25°C		
DC22b	7	8.5	mA	+85°C		
DC22c	7	8.5	mA	+125°C		
DC23d	13.2	17	mA	-40°C	3.3V	10 MIPS(3)
DC23a	13.2	17	mA	+25°C		
DC23b	13.2	17	mA	+85°C		
DC23c	13.2	17	mA	+125°C		
DC24d	17	22	mA	-40°C	3.3V	16 MIPS
DC24a	17	22	mA	+25°C		
DC24b	17	22	mA	+85°C		
DC24c	17	22	mA	+125°C		

Note 1: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

2: IDD is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDD measurements are as follows:

- Oscillator is configured in EC mode, OSC1 is driven with external square wave from rail-to-rail
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (PMDx bits are all zeroed)
- CPU executing `while(1)` statement

3: These parameters are characterized, but not tested in manufacturing.

TABLE 26-44: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING REQUIREMENTS FOR dsPIC33FJ32(GP/MC)10X

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP70	TscP	Maximum SCKx Input Frequency	—	—	11	MHz	See **Note 3**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance	10	—	50	ns	See **Note 4**
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	See **Note 4**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 91 ns. Therefore, the SCKx clock generated by the Master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

TABLE 26-45: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic**		**Min(1)**	**Max**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TCY/2 (BRG + 1)	—	μs	
			400 kHz mode	TCY/2 (BRG + 1)	—	μs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	μs	
IM11	THI:SCL	Clock High Time	100 kHz mode	TCY/2 (BRG + 1)	—	μs	
			400 kHz mode	TCY/2 (BRG + 1)	—	μs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	μs	
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	
			400 kHz mode	100	—	ns	
			1 MHz mode(2)	40	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	μs	
			400 kHz mode	0	0.9	μs	
			1 MHz mode(2)	0.2	—	μs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	μs	Only relevant for Repeated Start condition
			400 kHz mode	TCY/2 (BRG + 1)	—	μs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	μs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	μs	After this period the first clock pulse is generated
			400 kHz mode	TCY/2 (BRG + 1)	—	μs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	μs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	μs	
			400 kHz mode	TCY/2 (BRG + 1)	—	μs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	μs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	ns	
			400 kHz mode	TCY/2 (BRG + 1)	—	ns	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	ns	
IM40	TAA:SCL	Output Valid from Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
			1 MHz mode(2)	—	400	ns	
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
			1 MHz mode(2)	0.5	—	μs	
IM50	CB	Bus Capacitive Loading		—	400	pF	
IM51	TPGD	Pulse Gobbler Delay		65	390	ns	See **Note 3**

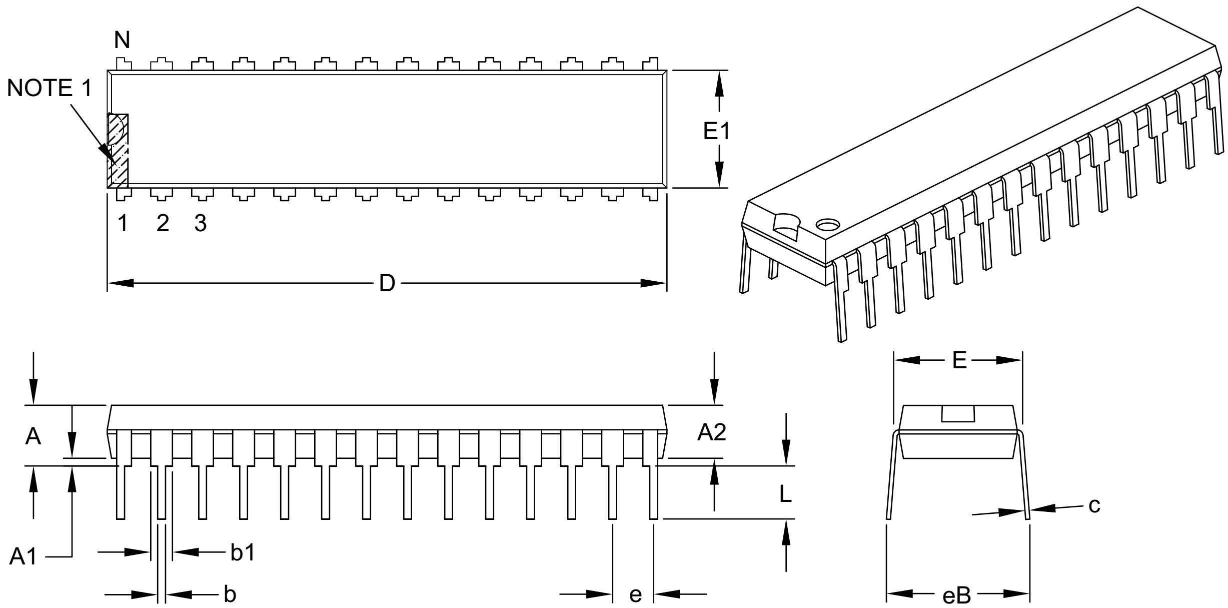
Note 1: BRG is the value of the I^{2}C™ Baud Rate Generator. Refer to **"Inter-Integrated Circuit (I^{2}C™)"** (DS70195) in the "*dsPIC33/PIC24 Family Reference Manual".* Please see the Microchip web site for the latest *"dsPIC33/PIC24 Family Reference Manual"* sections.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: Typical value for this parameter is 130 ns.

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



		Units	INCHES	
	Dimension Limits	MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

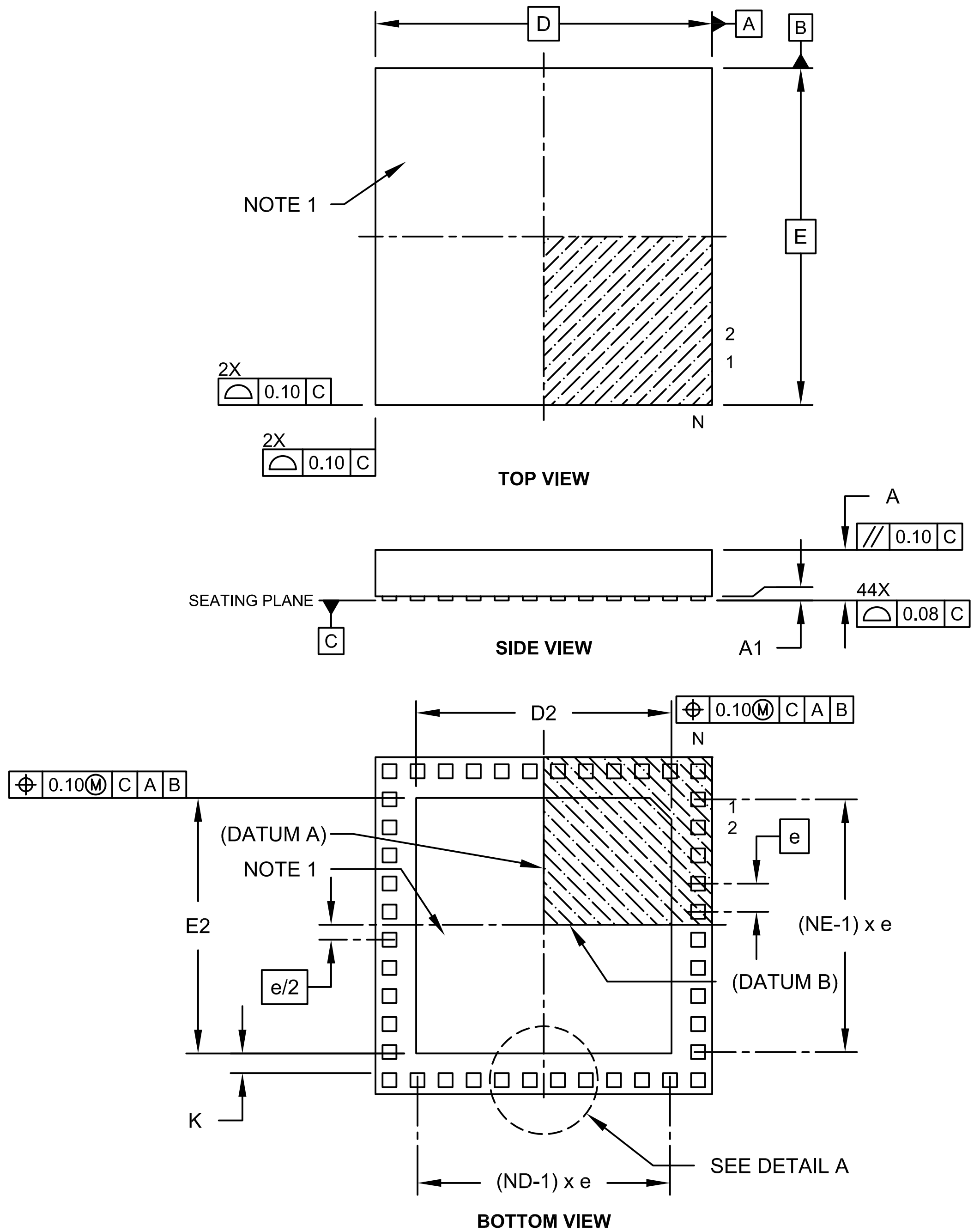
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-157C Sheet 1 of 2

Revision C (June 2011)

This revision includes the following global update:

- All JTAG references have been removed

All other major changes are referenced by their respective section in Table A-2.

In addition, minor text and formatting changes were incorporated throughout the document.

TABLE A-2: MAJOR SECTION UPDATES

Section Name	Update Description
High-Performance, Ultra Low Cost 16-bit Digital Signal Controllers	The TMS, TDI, TDO, and TCK pin names were removed from these pin diagrams: • 28-pin SPDIP/SOIC/SSOP • 28-pin QFN • 36-pin TLA
Section 1.0 “Device Overview”	Updated the Buffer Type to Digital for the CTED1 and CTED2 pins (see Table 1-1).
Section 4.0 “Memory Organization”	Updated the SFR Address for IC2CON, IC3BUF, and IC3CON in the Input Capture Register Map (see Table 4-7). Added the VREGS bit to the RCON register in the System Control Register Map (see Table 4-27).
Section 6.0 “Resets”	Added the VREGS bit to the RCON register (see Register 6-1).
Section 8.0 “Oscillator Configuration”	Updated the definition for COSC<2:0> = `001` and NOSC<2:0> = `001` in the OSCCON register (see Register 8-1).
Section 15.0 “Motor Control PWM Module”	Updated the title for Example 15-1 to include a reference to the Assembly language. Added Example 15-2, which provides a C code version of the write-protected register unlock and Fault clearing sequence.
Section 19.0 “10-bit Analog-to-Digital Converter (ADC)”	Updated the CH0 section and added Note 2 in both ADC block diagrams (see Figure 19-1 and Figure 19-2). Updated the multiplexer values in the ADC Conversion Clock Period Block Diagram (see Figure 19-3. Added the `01110` bit definitions and updated the `01101` bit definitions for the CH0SB<4:0> and CH0SA<4:0> bits in the AD1CHS0 register (see Register 19-5).
Section 22.0 “Charge Time Measurement Unit (CTMU)”	Removed Section 22.1 “Measuring Capacitance”, Section 22.2 “Measuring Time”, and Section 22.3 “Pulse Generation and Delay” Updated the key features. Added the CTMU Block Diagram (see Figure 22-1). Updated the ITRIM<5:0> bit definitions and added Note 1 to the CTMU Current Control register (see Register 22-3).